In the claims:

Please amend the claims to read as follows:

Claims 1 - 4 (cancelled).

5. (Currently amended) Platinum temperature sensor comprising:

a fired ceramic substrate;

a platinum thin-film resistor applied to the ceramic substrate;

a fired ceramic cover layer; and

a connecting layer made of a glaze comprising a glass that is applied to the ceramic substrate in a frame-like shape in a boarder area surrounding the platinum thin-film resistor by means of which the ceramic cover layer is connected with the ceramic substrate in such way that the platinum thin-film resistor is sealingly encapsulated with regard to the environment, wherein an interior portion of the connecting layer defines a void within which the platinum thin-film resistor is disposed, and wherein the connecting layer is produced by arranging the frame-like shaped glaze between the fired ceramic substrate and the fired ceramic cover layer and subjecting the glaze to a temperature treatment under application of pressure ~~a portion of the ceramic layer coincident with the void defined by the interior portion of the connecting layer is disposed directly adjacent to the platinum thin-film resistor~~ .

Claims 6-13 (canceled)

14. (Original) Platinum temperature sensor according to claim 5 wherein the ceramic substrate is made of Al_2O_3.

15. (Original) Platinum temperature sensor according to claim 5 wherein the ceramic cover layer is made of Al_2O_3.

16. (Original) Platinum temperature sensor according to claim 5 wherein a sealing cover is applied to the outer peripheral edges of the layer structure consisting of the ceramic substrate, the connecting layer and the ceramic cover layer.

17. (Original) Platinum temperature sensor according to claim 16 wherein the sealing cover is made of glass.

Add the following new claim 18:

18. (New) A method for producing a platinum temperature sensor comprising the steps of:

a) providing a fired ceramic substrate with a platinum thin-film resistor applied to the main surface thereof;

b) applying a connecting layer made of a glaze to the main surface of the ceramic substrate in an area surrounding the platinum thin-film resistor in a frame-like shape; and

c) applying a fired ceramic cover layer to the connecting layer so that the platinum thin-film resistor is sealingly encapsulated with regard to the environment by subjecting the glaze to a temperature treatment under application of pressure thereby connecting the ceramic substrate and the ceramic cover layer.